

Carrier with Metal Bumps for Semiconductor Die Packages

ABSTRACT OF THE DISCLOSURE

A carrier for a semiconductor die package is disclosed. In one embodiment, the carrier includes a metal layer and a plurality of bumps formed in the metal layer. The 5 bumps can be formed by stamping.

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Went out at 10:00 a.m. to see the new bridge. It is 40 ft. long and 14 ft. wide. It is made of timber and has a wooden railing.